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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masatake NAKANO et al.

Application No.: 09/857,569

Filed: June 7, 2001

Docket No.: 109716

For: METHOD FOR PRODUCING BONDING WAFER AND BONDING WAFER

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INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 CFR §1.56, the attention of the Patent and Trademark Office is hereby directed to the reference(s) listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- ☒ 1. This Information Disclosure Statement is being filed (a) within three months of the U.S. filing date of this non-CPA application, OR (b) before the mailing date of a first Office Action on the merits in the present application. No certification or fee is required.
- ☒ 2. The references were cited in a counterpart foreign application. An English language version of the foreign search report is attached for the Examiner's information.
- ☒ 3. An English-language Abstract of the non-English language reference No. 2 is attached hereto.

Respectfully submitted,

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WPB:TJP/tmw

Date: July 15, 2003

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European Patent  
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SUPPLEMENTARY  
EUROPEAN SEARCH REPORT

Application Number  
EP 00 96 3000

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.7)
Y	BRUEL M ET AL: "SMART-CUT: A NEW SILICON ON INSULATOR MATERIAL TECHNOLOGY BASED ON HYDROGEN IMPLANTATION AND WAFER BONDING" JAPANESE JOURNAL OF APPLIED PHYSICS, PUBLICATION OFFICE JAPANESE JOURNAL OF APPLIED PHYSICS. TOKYO, JP, vol. 36, no. 3B, PART 1, 1 March 1997 (1997-03-01), pages 1636-1641, XP000703088 ISSN: 0021-4922 * page 1639, left-hand column, line 29 - line 31; figure 1 *	1-7	H01L27/12 H01L21/762
Y	US 5 494 849 A (BARAN EMIL ET AL) 27 February 1996 (1996-02-27)	1-4,7	
X	* column 4, line 48 - line 64; figures 1-7 *	8,9	
Y	EP 0 444 942 A (SHINETSU HANDOTAI KK) 4 September 1991 (1991-09-04) * column 4, line 44 - column 7, line 2; figures 1-7 *	1,2,5,6	
X		8,9	TECHNICAL FIELDS SEARCHED (Int.Cl.7)
A	PATENT ABSTRACTS OF JAPAN vol. 1999, no. 04, 30 April 1999 (1999-04-30) & JP 11 026336 A (SUMITOMO METAL IND LTD), 29 January 1999 (1999-01-29) * abstract *	1-9	H01L
A	EP 0 451 993 A (SHINETSU HANDOTAI KK) 16 October 1991 (1991-10-16) * figures 1-3 *	1-9	
The supplementary search report has been based on the last set of claims valid and available at the start of the search.			
Place of search MUNICH		Date of completion of the search 20 May 2003	Examiner Götz, A
CATEGORY OF CITED DOCUMENTS			
X: particularly relevant if taken alone Y: particularly relevant if combined with another document of the same category A: technological background O: non-written disclosure P: intermediate document		T: theory or principle underlying the invention E: earlier patent document, but published on, or after the filing date D: document cited in the application L: document cited for other reasons ..... & : member of the same patent family, corresponding document	

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EPO FORM 1503 03.02 (P04C04)

ANNEX TO THE EUROPEAN SEARCH REPORT  
ON EUROPEAN PATENT APPLICATION NO.

EP 00 96 3000

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report. The members are as contained in the European Patent Office EDP file on  
The European Patent Office is in no way liable for these particulars which are merely given for the purpose of information.

20-05-2003

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			JP	11502674 T	02-03-1999
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Sheet 1 of 1

Form PTO-1449 (REV. 8-83)		US Dept. of Commerce PATENT & TRADEMARK OFFICE		ATTY DOCKET NO. 109716		APPLICATION NO. 09/857,569	
INFORMATION DISCLOSURE STATEMENT  (Use several sheets if necessary)				APPLICANTS Masatake NAKANO et al.		RECEIVED JUL 16 2003 GROUP 1700	
				FILING DATE June 7, 2001			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	
	1	5,494,849	02/27/1996	Iyer et al.			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	
	2	JP A 11-026336 (abstract only)	01/29/1999	Japan			
	3	EP 0 451 993 A2	10/16/1991	Europe			
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
	4	M. Bruel et al., "Smart-Cut: A New Silicon On Insulator Material Technology Based on Hydrogen Implantation and Wafer Bonding", Jpn. J. Appl. Phys., Vol 36, 1997, pp 1636-1641					
EXAMINER					DATE CONSIDERED		
Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Date: July 15, 2003